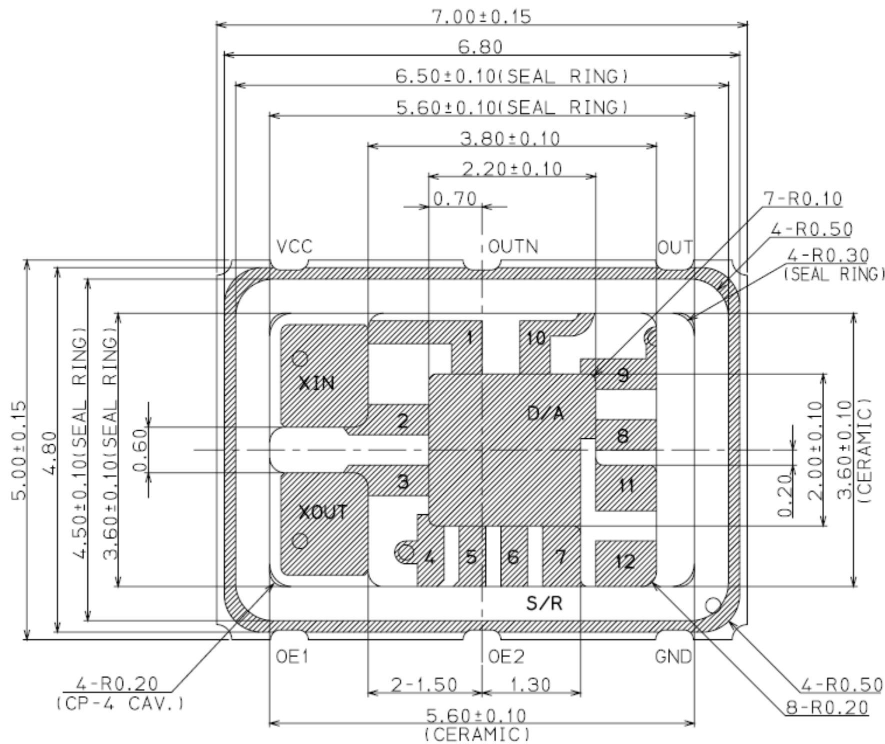

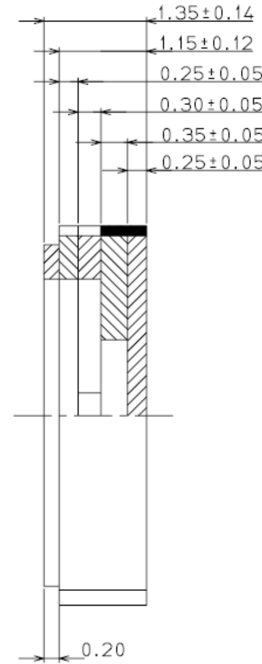

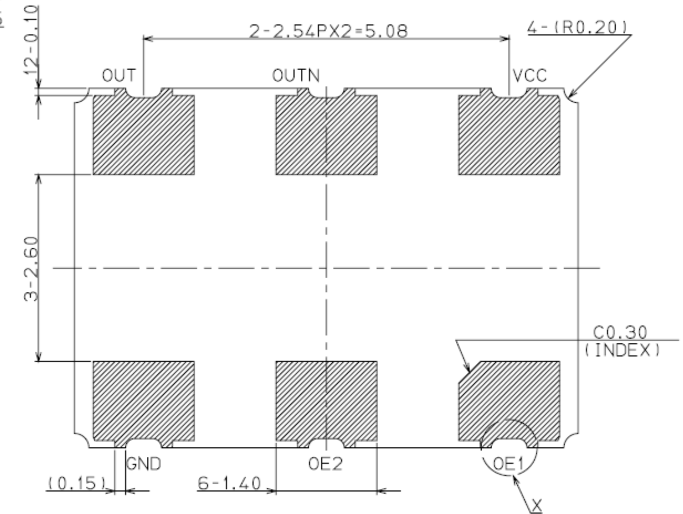

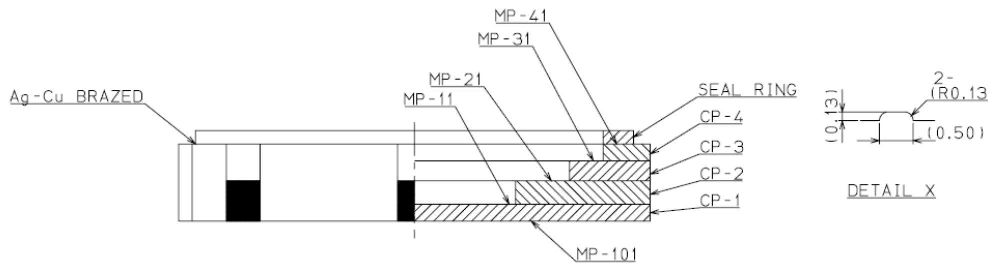

1. Plating Thickness		Electro Nickel Ni: 1.27 – 8.89 micron (Solder Pads) Electro Gold Au: 0.70-1.20 micron (Solder Pads)
2. Connection		1-8-11-VCC, 2-Xin, 3-Xout, 4-7-12-Gnd-S/R-D/A, 5-OE, 6-OE2, 9-OutN, 10-Out
3. Camber		50.00 micron maximum
Exposure of ceramic surface occurring by misalignment of the upper layer shall be allowed.		
▬ indicates the side metalized pattern		
Stress Relaxation design shall be applied on this item		
Sealing Method of this product shall be seam weld.		

Type	Sub-type	Description		S5070DCK2
Design	Check	Approved	Rev.	
AB	ER	TH	A	VCAmerica
		11/3/07		